2020 2

Course Title	()	() Semi	conductor Fabrication Processes		
() Lecturer	()	/ / (Course No./)	006147/ /3		
(/HP) Contact No.		/ (Class Hour/Venue)	13:30-15:00		
(Course Prerequisite)		(Target Student)	3		
E-mail (E-mail Address)		/Office Hour (Office/Office Hour)	812 / 15:00-17:00		
		<u> </u>			
(Objectives)	(crystal growth, cleaning, lithography, oxidation, diffusion, ion implantation, thin film deposition, etching, back-end processing) . Term Project				
(Competencies related to this course) CQI (Continuous Quality Improvement Plan)	 ✓ (Logical and Critical Thinking) ✓ (Creative and Convergent Thinking) ☐ (Self-management Competency) ✓ (Problem Solving Competency) ☐ (Communication Competency) ☐ (Global Competency) ☐ (Community Competency) ✓ (Community Competenc				
(Text book)					
(Assignment book)	- Plummer et al., "Silicon VLSI Technology: Fundamentals, Practice, and Modeling", Prentice Hall (2000) - "Silicon Run" VTR tape () - Doering and Nishi(ed), "Handbook of Semiconductor Manufacturing Technology" (2007)				
(Assignment) - フト		1 pdf noint %): 40, フト (%): 2	20, (%): 10, -		

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(Week)	(Course Contents)	(Etc.)	
1	Introduction and Historical Perspective		
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2	Modern CMOS Technology		
3	CMOS Process Flow		
4	Fabrication and Basic Properties of Silicon Wafers		
5	Clean Rooms, Wafer Cleaning, and Gettering		
	Lithography		
6	Lithography		
	Thermal Oxidation and the Si/SiO2 Interface		
7	The man extraction and the 37/3/02 interface		
8			

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(Week)	(Course Contents)	(Etc.)	
	Dopant Diffusion		
9			
	Ion Implantation		
10			
	Thin Film Deposition I		
11			
	Thin Film Deposition II		
12			
	Etching		
13			
	Interconnect		
14			
	3D Devices		
15			
16			

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가 1 (Additional Guide1)	8 3 50 (2 ,)			
7† 2 (Additional Guide2)	7† 0' - term paper F' 0 0 (, ,)			